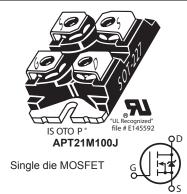




1000V, 21A, 0.38Ω Max

N-Channel MOSFET

Power MOS 8^{TM} is a high speed, high voltage N-channel switch-mode power MOSFET. A proprietary planar stripe design yields excellent reliability and manufacturability. Low switching loss is achieved with low input capacitance and ultra low C_{rss} "Miller" capacitance. The intrinsic gate resistance and capacitance of the poly-silicon gate structure help control slew rates during switching, resulting in low EMI and reliable paralleling, even when switching at very high frequency. Reliability in flyback, boost, forward, and other circuits is enhanced by the high avalanche energy capability.



FEATURES

- · Fast switching with low EMI/RFI
- Low R_{DS(on)}
- Ultra low C_{rss} for improved noise immunity
- · Low gate charge
- · Avalanche energy rated
- RoHS compliant

TYPICAL APPLICATIONS

- · PFC and other boost converter
- Buck converter
- Two switch forward (asymmetrical bridge)
- · Single switch forward
- Flyback
- · Inverters

Absolute Maximum Ratings

Symbol	Parameter	Ratings	Unit
L	Continuous Drain Current @ T _C = 25°C	21	
'D	Continuous Drain Current @ T _C = 100°C	13	А
I _{DM}	Pulsed Drain Current ^①	120	
V _{GS}	Gate-Source Voltage	±30	٧
E _{AS}	Single Pulse Avalanche Energy ©	1875	mJ
I _{AR}	Avalanche Current, Repetitive or Non-Repetitive	16	Α

Thermal and Mechanical Characteristics

Symbol	Characteristic	Min	Тур	Max	Unit
P _D	Total Power Dissipation @ T _C = 25°C			462	W
R _{eJC}	Junction to Case Thermal Resistance			0.27	°C/W
R _{ecs}	Case to Sink Thermal Resistance, Flat, Greased Surface		0.15		C/VV
T _J ,T _{STG}	Operating and Storage Junction Temperature Range	-55		150	°C
V _{Isolation}	RMS Voltage (50-60hHz Sinusoidal Wavefomr from Terminals to Mounting Base for 1 Min.)	2500			V
W _T	Package Weight		1.03		OZ
			29.2		g
Torque	Terminals and Mounting Screws.			10	in·lbf
				1.1	N·m

Static Characteristics

T_J = 25°C unless otherwise specified

AP	T21	M1	00	J
\sim	141	IAII	v	J

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
V _{BR(DSS)}	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_{D} = 250 \mu A$	1000			V
$\Delta V_{BR(DSS)} / \Delta T_{J}$	Breakdown Voltage Temperature Coefficient	Reference to 25°C, I _D = 250µA		1.15		V/°C
R _{DS(on)}	Drain-Source On Resistance [®]	V _{GS} = 10V, I _D = 16A		0.32	0.38	Ω
V _{GS(th)}	Gate-Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 2.5 \text{mA}$	3	4	5	V
$\Delta V_{GS(th)}/\Delta T_{J}$	Threshold Voltage Temperature Coefficient			-10		mV/°C
	Zero Gate Voltage Drain Current	$V_{DS} = 1000V$ $T_{J} = 25^{\circ}C$			100	μA
DSS		$V_{GS} = 0V$ $T_J = 125^{\circ}C$			500	μΛ
I _{GSS}	Gate-Source Leakage Current	V _{GS} = ±30V			±100	nA

Dvnamic Characteristics

T₁ = 25°C unless otherwise specified

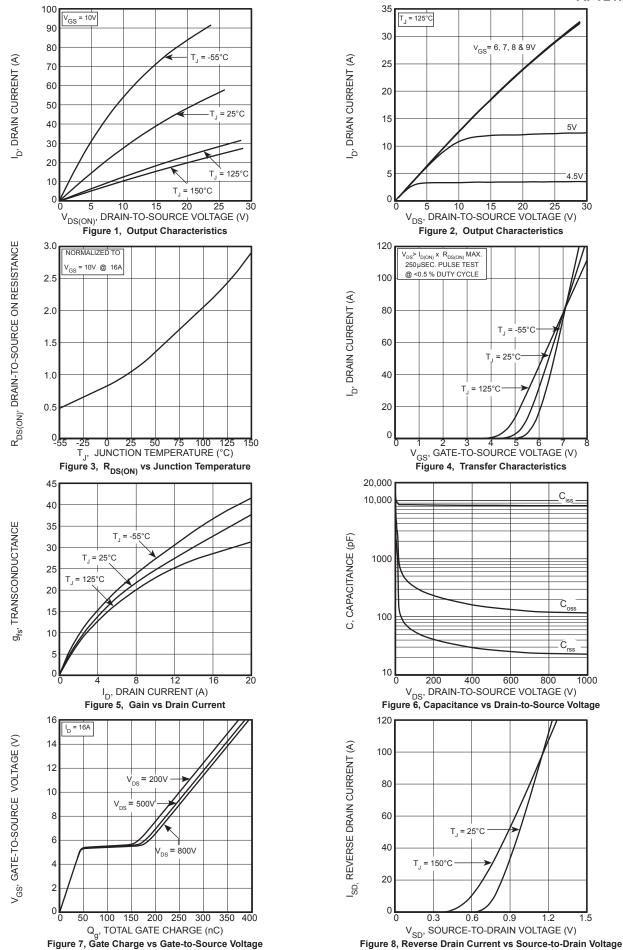
Symbol	Parameter	arameter Test Conditions		Тур	Max	Unit
g _{fs}	Forward Transconductance	V _{DS} = 50V, I _D = 16A		34		S
C _{iss}	Input Capacitance	V 0V V 05V		8500		
C _{rss}	Reverse Transfer Capacitance	$V_{GS} = 0V, V_{DS} = 25V$ f = 1MHz		115		
C _{oss}	Output Capacitance	1 111112		700		
$C_{o(cr)} @$	Effective Output Capacitance, Charge Related	V = 0V V = 0V to 667V		290		pF
C _{o(er)} ⑤	Effective Output Capacitance, Energy Related	V _{GS} = 0V, V _{DS} = 0V to 667V		150		
Q _g	Total Gate Charge)/ 01: 40\/ 1 40A		260		
Q_{gs}	Gate-Source Charge	$V_{GS} = 0 \text{ to } 10V, I_{D} = 16A,$ $V_{DS} = 500V$		46		nC
Q_{gd}	Gate-Drain Charge	V _{DS} = 500V		125		
t _{d(on)}	Turn-On Delay Time	Resistive Switching		39		
t _r	Current Rise Time	V _{DD} = 667V, I _D = 16A		35		ns
t _{d(off)}	Turn-Off Delay Time	$R_{G} = 2.2\Omega^{\textcircled{6}}, V_{GG} = 15V$		130		115
t _f	Current Fall Time			33		

Source-Drain Diode Characteristics

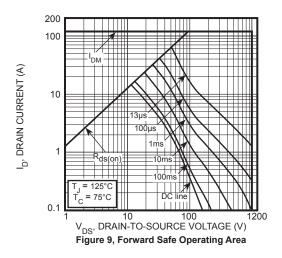
Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
Is	Continuous Source Current (Body Diode)	MOSFET symbol showing the			21	A
I _{SM}	Pulsed Source Current (Body Diode) (1)	integral reverse p-n junction diode (body diode)			120	A
V _{SD}	Diode Forward Voltage	$I_{SD} = 16A, T_{J} = 25^{\circ}C, V_{GS} = 0V$			1	V
t _{rr}	Reverse Recovery Time	I _{SD} = 16A ^③		1140		ns
Q _{rr}	Reverse Recovery Charge	$di_{SD}/dt = 100A/\mu s$, $T_J = 25$ °C		30		μC
dv/dt	Peak Recovery dv/dt	$I_{SD} \le 16A$, di/dt $\le 1000A/\mu s$, $V_{DD} = 667V$, $T_{J} = 125^{\circ}C$			10	V/ns

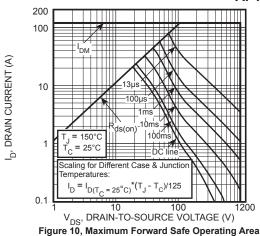
- (1) Repetitive Rating: Pulse width and case temperature limited by maximum junction temperature.
- ② Starting at $T_J = 25$ °C, L = 14.65mH, $R_G = 2.2\Omega$, $I_{AS} = 16A$.
- ③ Pulse test: Pulse Width < 380μs, duty cycle < 2%.
- $\begin{array}{l} \textcircled{4} \quad \text{$C_{o(cr)}$ is defined as a fixed capacitance with the same stored charge as C_{OSS} with V_{DS} = 67% of $V_{(BR)DSS}$.} \\ \textcircled{5} \quad \text{$C_{o(er)}$ is defined as a fixed capacitance with the same stored energy as C_{OSS} with V_{DS} = 67% of $V_{(BR)DSS}$.} \\ \textbf{V_{DS} less than $V_{(BR)DSS}$, use this equation: $C_{o(er)}$ = -2.47E-7/V_{DS}^2 + 4.36E-8/V_{DS} + 8.44E-11.} \\ \end{array}$
- (6) R_G is external gate resistance, not including internal gate resistance or gate driver impedance. (MIC4452)

Microsemi reserves the right to change, without notice, the specifications and information contained herein.



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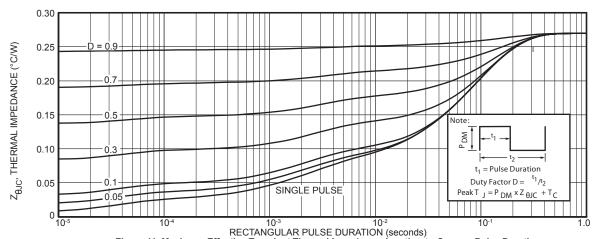
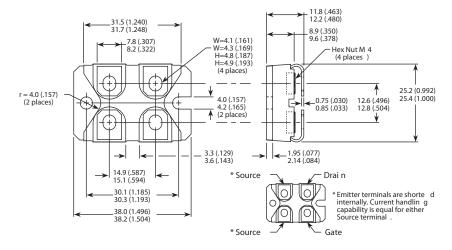


Figure 11. Maximum Effective Transient Thermal Impedance Junction-to-Case vs Pulse Duration

SOT-227 (ISOTOP®) Package Outline



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25.163.2453.	0 25.163.4253.0	25.190.2053.0	25.194.3453.0	25.320.4853.1	25.320.5253.1	25.326.3253.1	25.326.3553.1	25.330.1653.1
25.330.4753.	1 25.330.5253.1	25.334.3253.1	25.334.3353.1	25.350.2053.0	25.352.4753.1	25.522.3253.0	T483C T484C	<u>T485F</u> <u>T485H</u>
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25.640.5053.	0							